

PRE-PRODUCT CHANGE NOTICE

产品变更申请

PCN#编号:	PCN#20240715-001	Date 日期:	2024/07/15		
Subject 主题: 关于 CA-IS3211XX 系列产品 SOIC6-WB 封装框架工艺升级的 pre-PCN Pre-PCN of SOIC6-WB package lead frame process upgrade for CA-IS3211XX series products					
Originator 发起人:	Taotao Gu	Phone 电话:	+86-021-50838601	Dept.部门:	封装工程
Change Details 变更说明					
Change Classification 变更等级:		<input checked="" type="checkbox"/> 一级变更 <input type="checkbox"/> 二级变更 <input type="checkbox"/> 三级变更 <input type="checkbox"/> 四级变更			
Change Type 变更类型: <input type="checkbox"/> Wafer Fabrication 晶圆制造 <input checked="" type="checkbox"/> Assembly 封装 <input type="checkbox"/> Test 测试 <input type="checkbox"/> Product Revision 产品改版 <input type="checkbox"/> Datasheet 产品规格书 <input type="checkbox"/> End of Line 停产 <input type="checkbox"/> Other 其它					
Description of Changes 变更描述: 框架工艺的变更，从蚀刻工艺升级为冲压工艺 Change in lead frame process, upgraded from etching process to stamping process 备注： 正式 PCN 时会提供变更前后框架 X-RAY 对比图 Remarks: X-RAY comparison of the lead frame before and after the change will be provided in the final PCN.					
Reason for Changes 变更原因: 1、此次工艺升级旨在通过先进的冲压技术，确保更一致的产品尺寸精度和更高的可靠性，从而加强我们产品的长期稳定性。 This process upgrade is designed to ensure more consistent product dimensional accuracy and higher reliability through advanced stamping technology, thus enhancing the long-term stability of our products. 2、通过转向冲压工艺，我们不仅优化了生产流程，减少了材料浪费，还提升了能效，这是我们对可持续发展承诺的一部分 By shifting to a stamping process, we have not only optimized our production processes and reduced material waste, but we have also improved energy efficiency as part of our commitment to sustainability. 3、此变更将使我们能够更快速地响应市场变化，缩短交货周期，增强我们的供应链管理，以更高效的方式支持您的业务需求 By shifting to a stamping process, we have not only optimized our production processes and reduced material waste, but we have also improved energy efficiency as part of our commitment to sustainability.					
Impact of the change (positive or negative) on fit, form, function & reliability 变更（正面或负面）对外观、尺寸、功能和可靠性的影响: 对产品外观、尺寸、功能和可靠性无影响 No effect on product appearance, dimensions, functionality and reliability.					
Affected Part Number 受影响产品型号: 1) 封装形式 package: SOIC6-WB 2) 产品型号 Product list: ✓ CA-IS3211VCJ ✓ CA-IS3211VBJ					
Verification Plan 验证计划:					

No.	Y2024										Y2025							
	WW29	WW30	WW43	WW44	WW45	WW46	WW47	WW48	WW49	WW50	WW51	WW52	WW01	WW02	WW03	WW04	WW05	WW06
内部变更评审 Internal CCB																		
Pre-PCN																		
框架验证 Lead frame verification																		
样品 Samples										样品提供 Sample ready								
封装可靠性 Package reliability verification																		
最终内部变更评审 Final CCB																		
PCN																		

Implementation Date 实施日期:

- 1) 样品提供: 预计 2024 年 12 月中旬提供
Sample availability: expected mid-December 2024
- 2) 量产切换: 预计工厂切换的日期为 2025 年 2 月底。
Volume production switchover: The expected date for plant switchover is the end of February 2025.

Appendix 附件:

Chipanalog Approval/Comment:

Approval Not approval Other

Date: 2024 年 07 月 15 日
Name/ title: Chen, Liang/Quality Director

Customer Approval/Comment:

Approval Not approval Other

Date:
Name/ title:

Remark: After Chipanalog notice of change is issued, for class 1 change, please review within 30 calendar days. For class 2 change, please review within 15 calendar days. If there is any problem, please feedback timely. If there is no feedback, you will agree to the change by default.
备注: 川土变更通知发出后, 一级变更请您在 30 天内进行评审, 二级变更请您在 15 天内进行评审。若有问题, 请您及时反馈。若未反馈, 默认您同意变更。

For additional information regarding this change, contact your local sales representative or contact the PCN administrator at chenliang@chipanalog.com.
有关此更改的其他信息, 请联系销售代表或 PCN 管理员: chenliang@chipanalog.com.